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(54) **Title:** MICROELECTROMECHANICAL DEVICE WITH OPTICAL FUNCTION SEPARATED FROM MECHANICAL AND ELECTRICAL FUNCTION

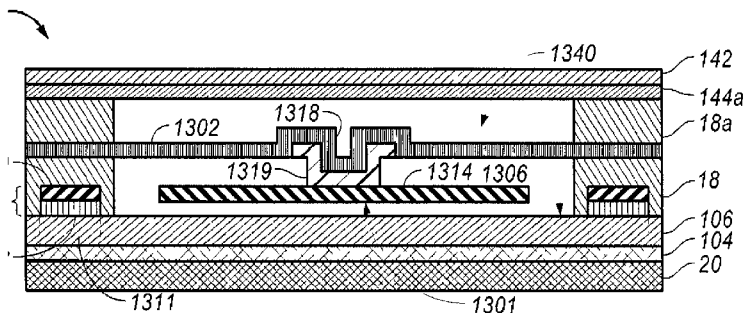


FIG. 13A

(57) **Abstract:** A microelectromechanical (MEMS) device (1300) includes a substrate (20), a movable element (1340) over the substrate (20), and an actuation electrode (142) above the movable element (1340). The movable element (1340) includes a deformable layer (1302) and a reflective element (1314). The deformable layer (1302) is spaced from the reflective element (1314).

WO 2009/006120 A8